

**AGENDA**  
**Soldering Technology Committee**  
**May 17, 2005 – 1:30PM**  
**Chateau Sonesta Hotel- New Orleans**

**1) Introductions and Roster modifications**

**2) October meeting minutes approval**

**2 Old business**

**3 New business**

**3.1 Revision to IPC/EIA J-STD-002B**

**3.1.1 J-STD-002C Status**

Work has been completed on the DOE which evaluated Pb-free solderability parameters. Dave Hillman will review the results of the DOE. Also, the team will review the proposed revisions to J-STD-002B for inclusion of Pb-free. Timing for review and update of the standard will be discussed.

**3.2 Possible replacements for steam pre-conditioning**

Committee members have agreed that an area for future work is the replacement of steam pre-conditioning. Investigation of industry data and other pre-condition methods in use will be needed. Mr. Hillman has indicated that he will support this activity.

**3.3 Gauge R&R for wetting balance test**

The wetting balance test method is currently listed in ANSI/J-STD-002 under the section "Tests without Established Accept/Reject Criterion". Input from Dave Hillman was that the IPC committee discussed the options of either validating or removing the wetting balance method as an accepted method. Team needs to discuss plans/timing for future work.

**4 Next meeting**

**5 Adjournment**

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